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(12) **United States Design Patent**
Shi et al.

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(45) **Date of Patent:** **** *Jul. 12, 2016**

(54) **PACKAGE FOR LIGHT-EMITTING DIODE**

(56) **References Cited**

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(*) Notice: This patent is subject to a terminal disclaimer.

(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(52) **U.S. Cl.**
USPC **D13/180**

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CPC ... H01L 25/167; H01L 25/0753; H01L 27/15;
H01L 27/156; H01L 31/02; H01L 33/00;
H01L 33/04; H01L 33/08; H01L 33/10;
H01L 33/20; H01L 33/38; H01L 33/42;
H01L 33/48; H01L 33/62; H01L 33/483;
H01L 33/486; F21K 9/00; F21K 9/30; F21K
9/54

See application file for complete search history.

U.S. PATENT DOCUMENTS

D476,961 S * 7/2003 Horiuchi D13/182
6,657,238 B2 * 12/2003 Ueda H01L 33/38
257/100
6,734,536 B2 * 5/2004 Kobayakawa H01L 21/4828
257/676
7,491,977 B2 * 2/2009 Fukasawa H01L 33/60
257/81
7,586,178 B2 * 9/2009 Manatad H01L 23/49844
257/666
D626,097 S * 10/2010 Takeuchi D13/180
D626,922 S * 11/2010 Wada D13/180
D629,767 S * 12/2010 Shimizu D13/180
D671,509 S * 11/2012 Moriguchi D13/180
D676,002 S * 2/2013 Watanabe D13/180
D694,201 S * 11/2013 Iino D13/180
D698,742 S * 2/2014 Niikura D13/180
D731,989 S * 6/2015 Huang D13/180
D742,554 S * 11/2015 Kanemaru D26/1
2002/0123163 A1 * 9/2002 Fujii H01L 33/486
438/26
2009/0057855 A1 * 3/2009 Quinones H01L 23/49551
257/676
2010/0059782 A1 * 3/2010 Fujitomo H01L 24/97
257/98
2012/0132933 A1 * 5/2012 Watari H01L 33/52
257/88

* cited by examiner

Primary Examiner — Selina Sikder

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(57) **CLAIM**

The ornamental design for a package for light-emitting diode, substantially as shown and described.

DESCRIPTION

FIG. 1 is a front view of a package for light emitting diode according to a first embodiment of the disclosure;
FIG. 2 is a rear view of a package for light emitting diode according to the first embodiment of the disclosure;
FIG. 3 is a left side view of a package for light emitting diode according to the first embodiment of the disclosure;

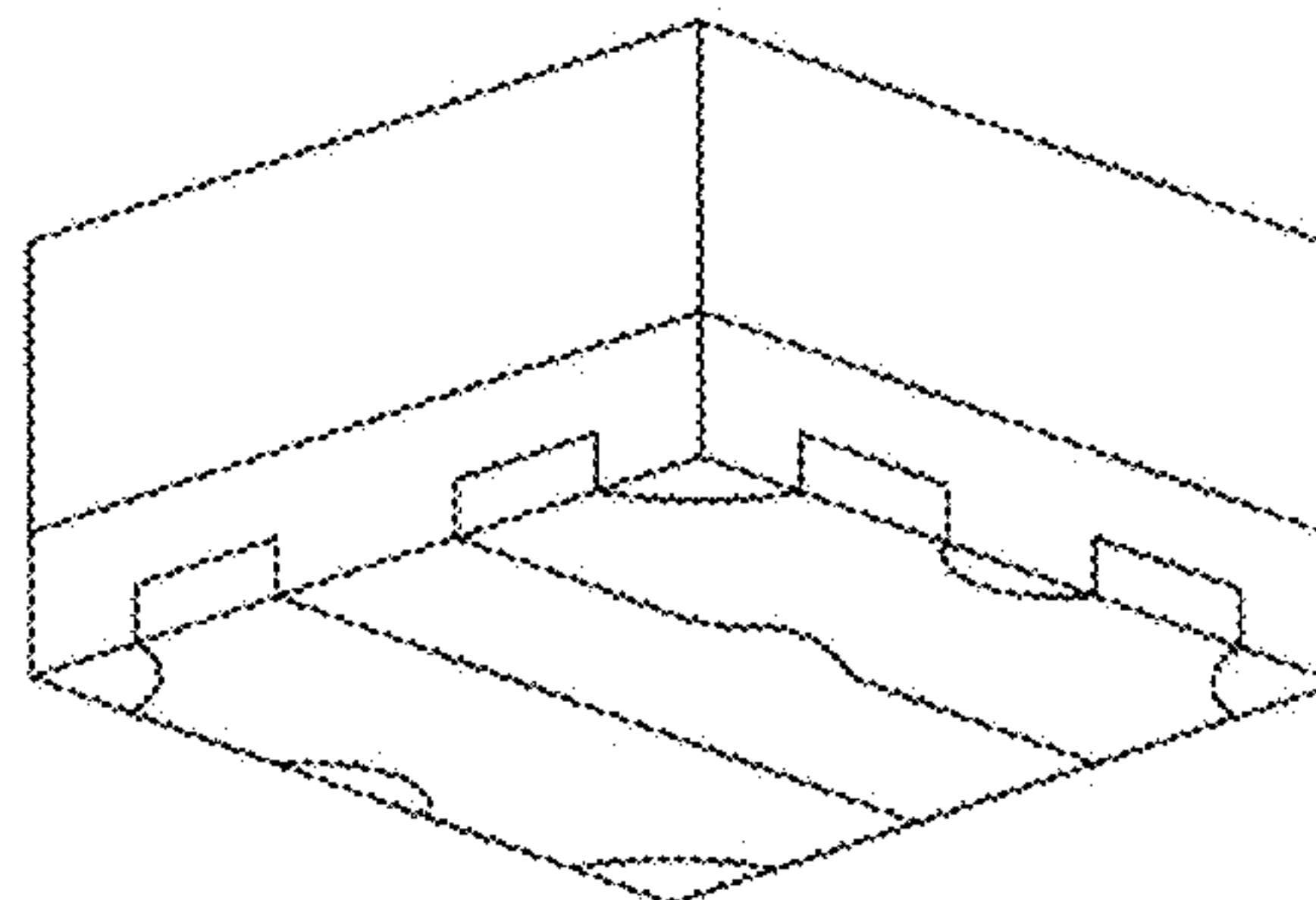
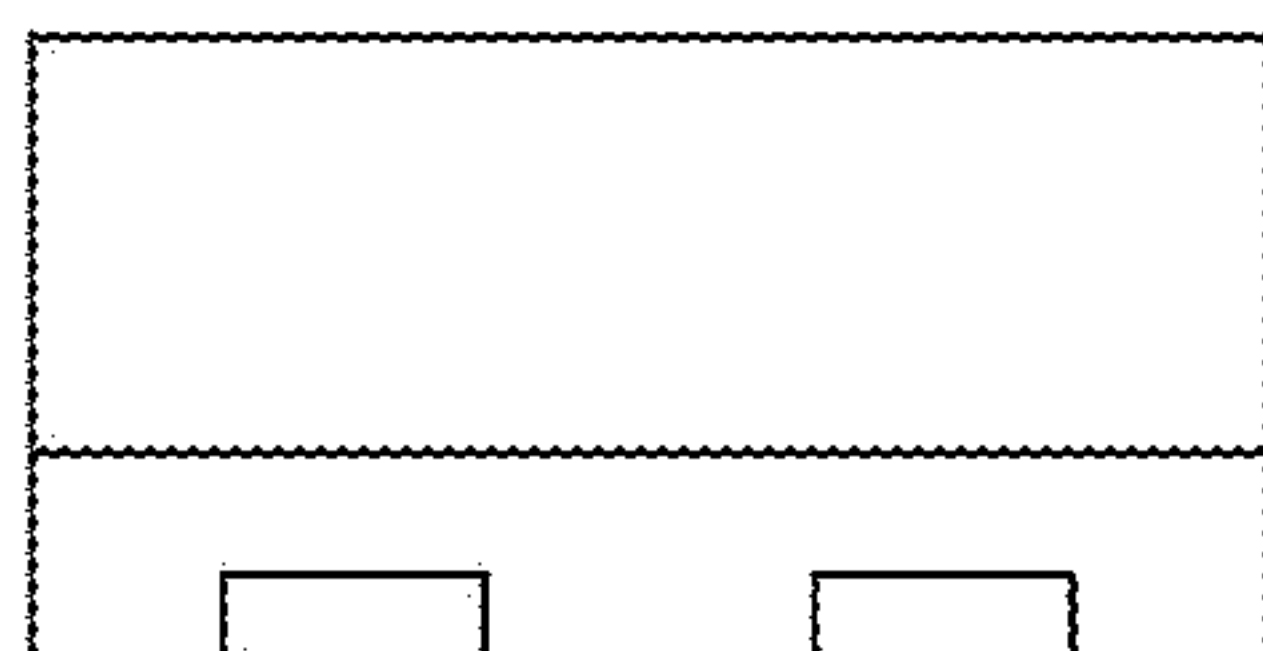


FIG. 4 is a right side view of a package for light emitting diode according to the first embodiment of the disclosure;
FIG. 5 is a top view of a package for light emitting diode according to the first embodiment of the disclosure;
FIG. 6 is a bottom view of a package for light emitting diode according to the first embodiment of the disclosure;
FIG. 7 is a perspective view of a package for light emitting diode according to the first embodiment of the disclosure;
FIG. 8 is another perspective view of a package for light emitting diode according to the first embodiment of the disclosure;
FIG. 9 is a front view of a package for light emitting diode according to a second embodiment of the disclosure;
FIG. 10 is a rear view of a package for light emitting diode according to the second embodiment of the disclosure;
FIG. 11 is a left side view of a package for light emitting diode according to the second embodiment of the disclosure;
FIG. 12 is a right side view of a package for light emitting diode according to the second embodiment of the disclosure;
FIG. 13 is a top view of a package for light emitting diode according to the second embodiment of the disclosure;
FIG. 14 is a bottom view of a package for light emitting diode according to the second embodiment of the disclosure;

FIG. 15 is a perspective view of a package for light emitting diode according to the second embodiment of the disclosure;
FIG. 16 is another perspective view of a package for light emitting diode according to the second embodiment of the disclosure;
FIG. 17 is a front view of a package for light emitting diode according to a third embodiment of the disclosure;
FIG. 18 is a rear view of a package for light emitting diode according to the third embodiment of the disclosure;
FIG. 19 is a left side view of a package for light emitting diode according to the third embodiment of the disclosure;
FIG. 20 is a right side view of a package for light emitting diode according to the third embodiment of the disclosure;
FIG. 21 is a top view of a package for light emitting diode according to the third embodiment of the disclosure;
FIG. 22 is a bottom view of a package for light emitting diode according to the third embodiment of the disclosure;
FIG. 23 is a perspective view of a package for light emitting diode according to the third embodiment of the disclosure;
and,
FIG. 24 is another perspective view of a package for light emitting diode according to the third embodiment of the disclosure.

1 Claim, 9 Drawing Sheets

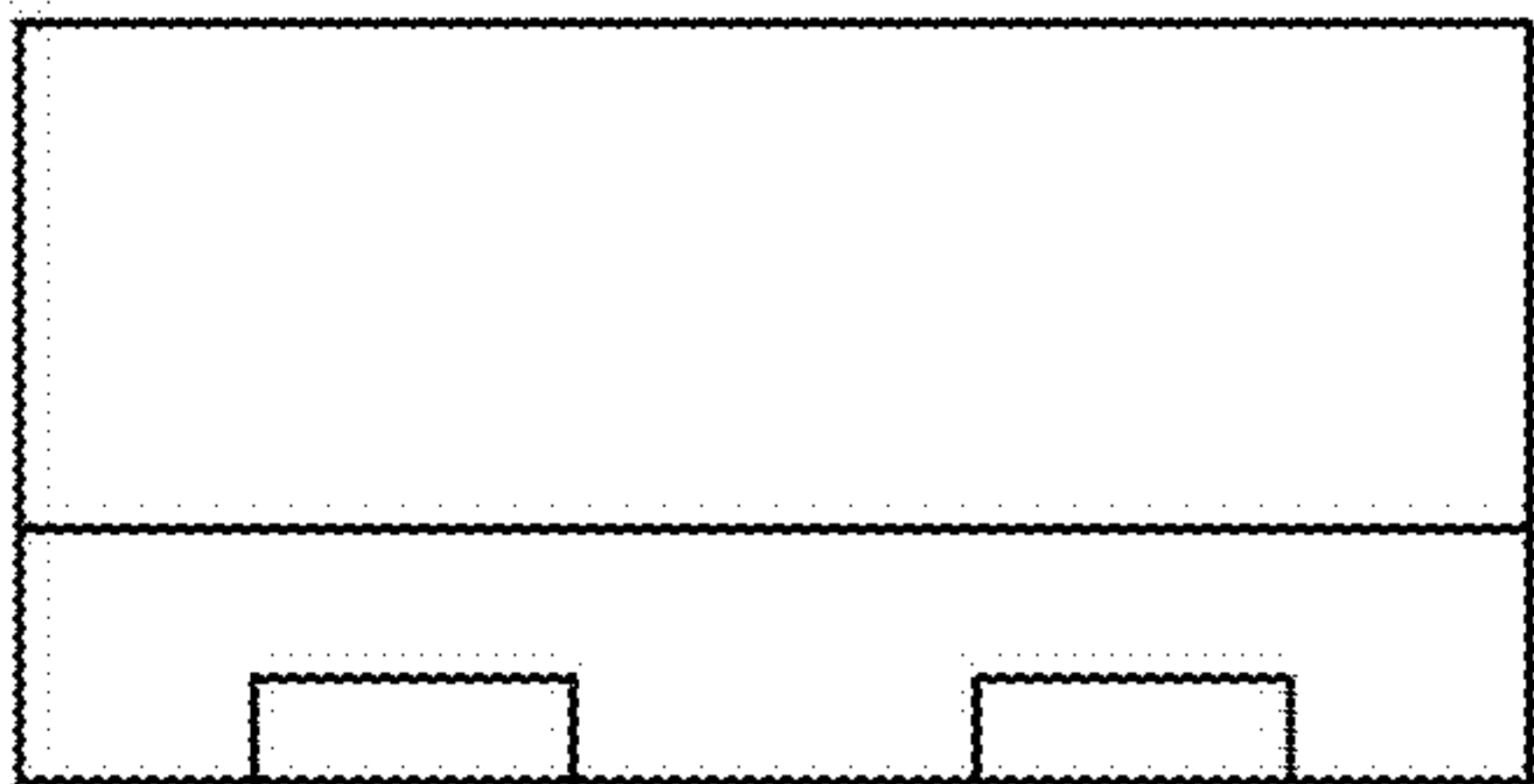


FIG. 1

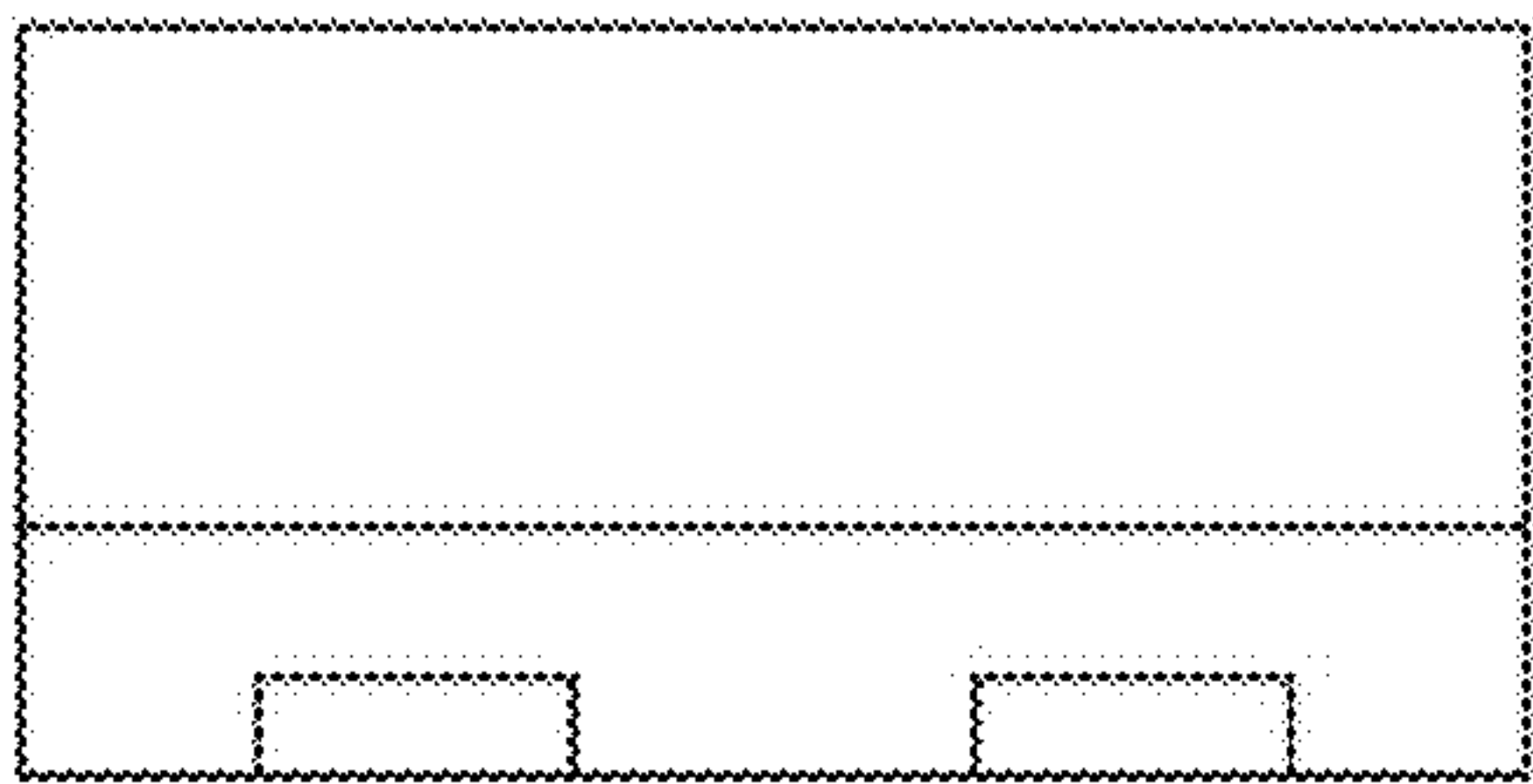


FIG. 2

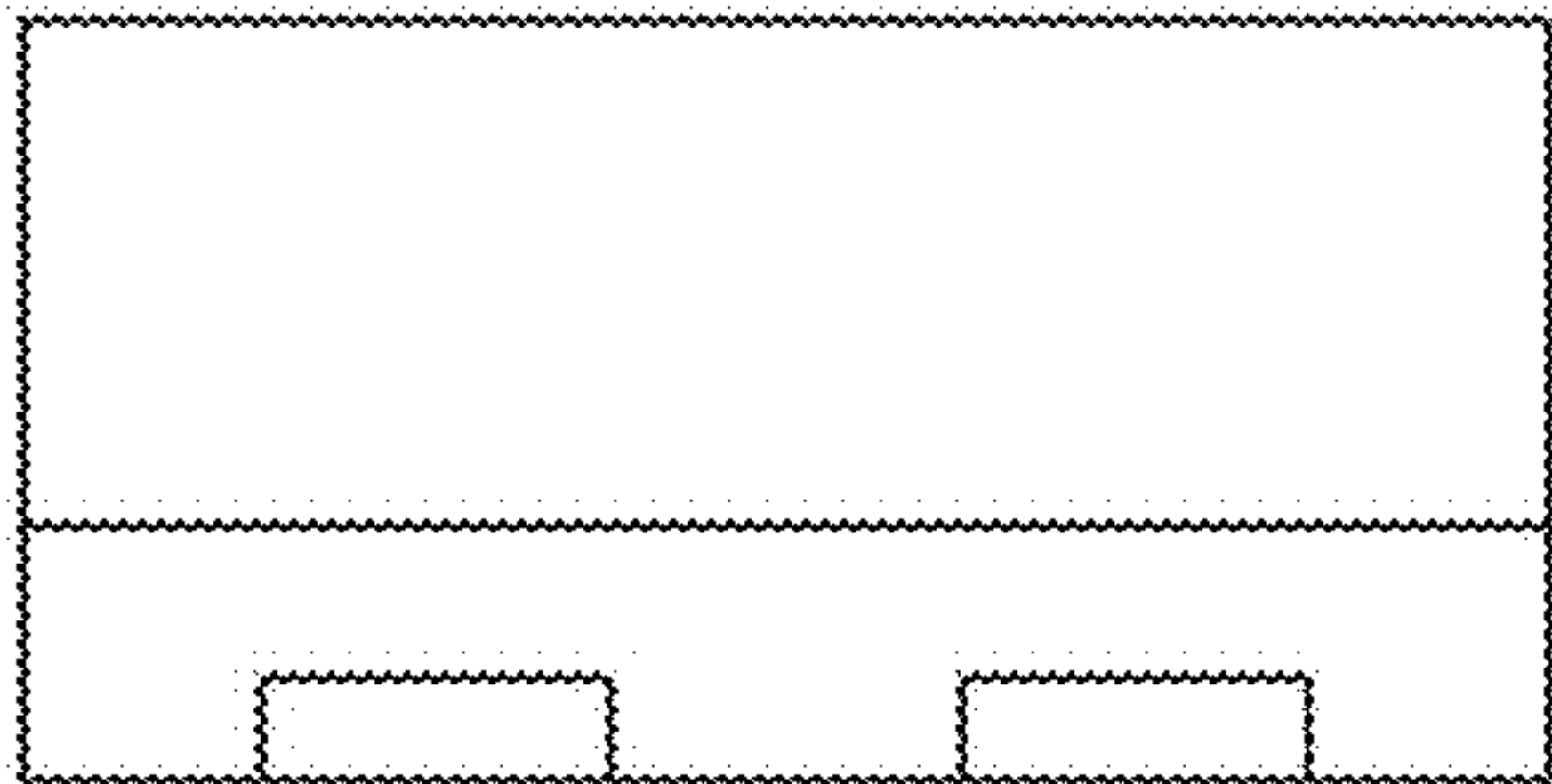


FIG. 3

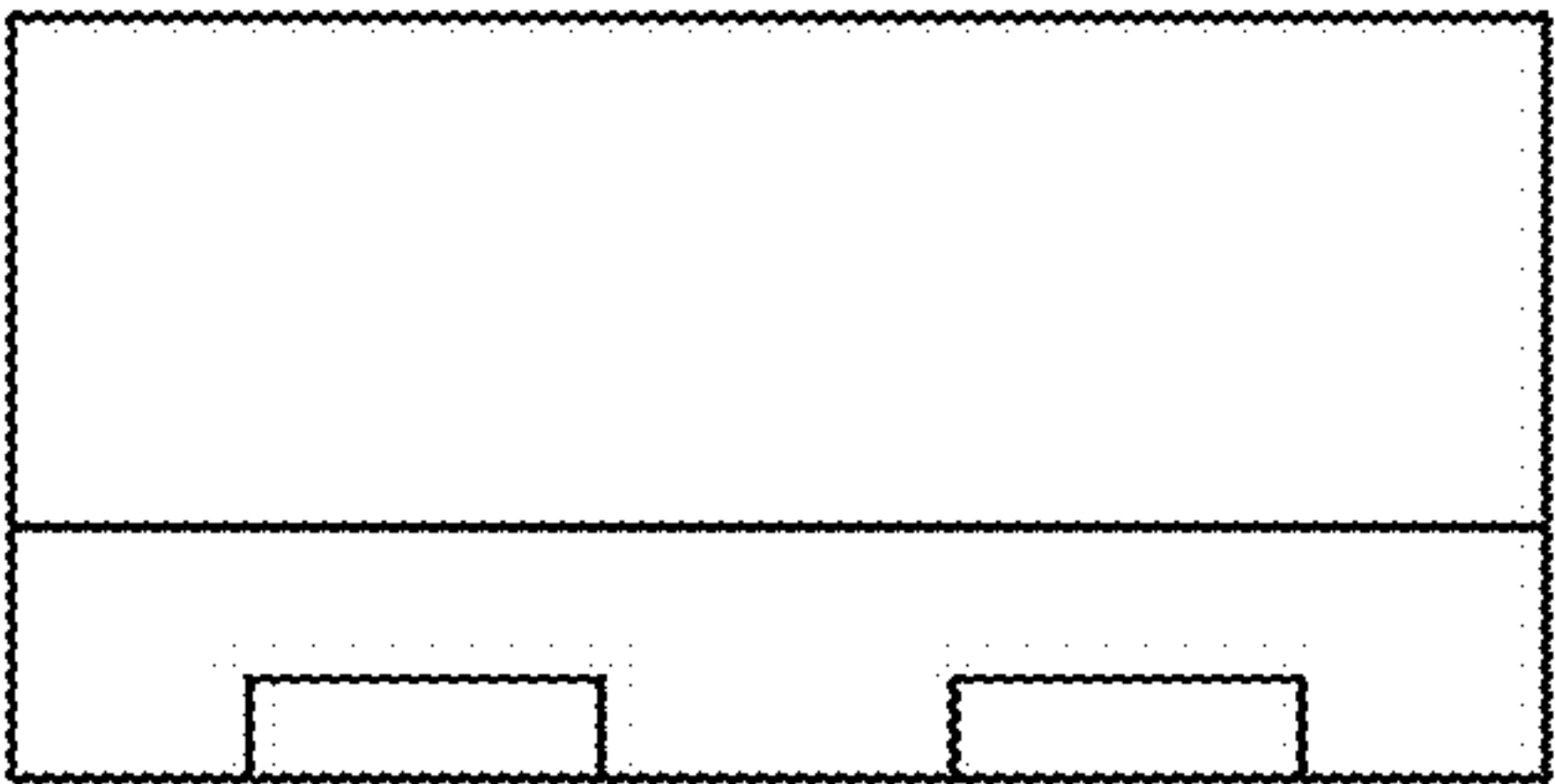


FIG. 4

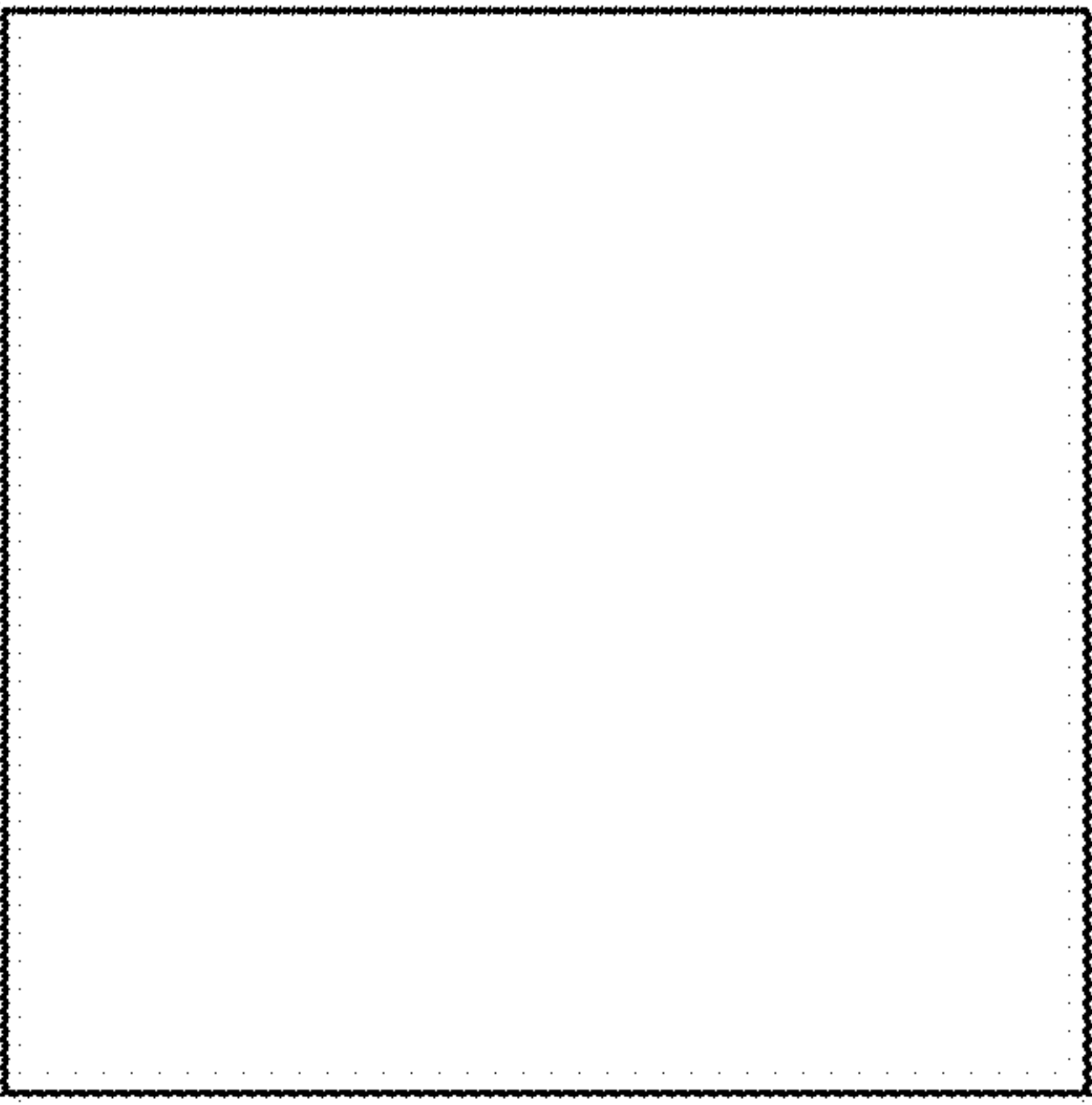


FIG. 5

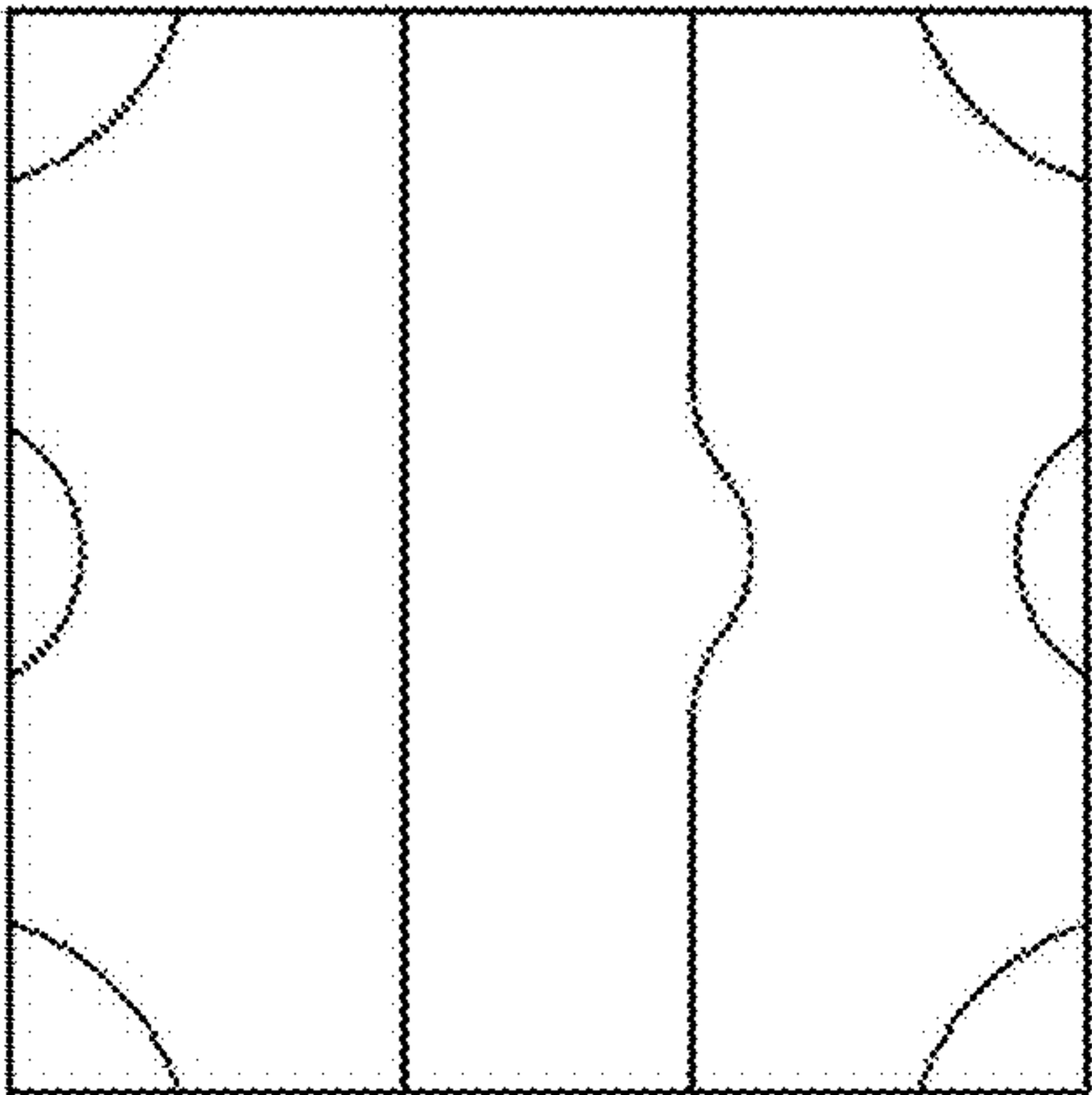


FIG. 6

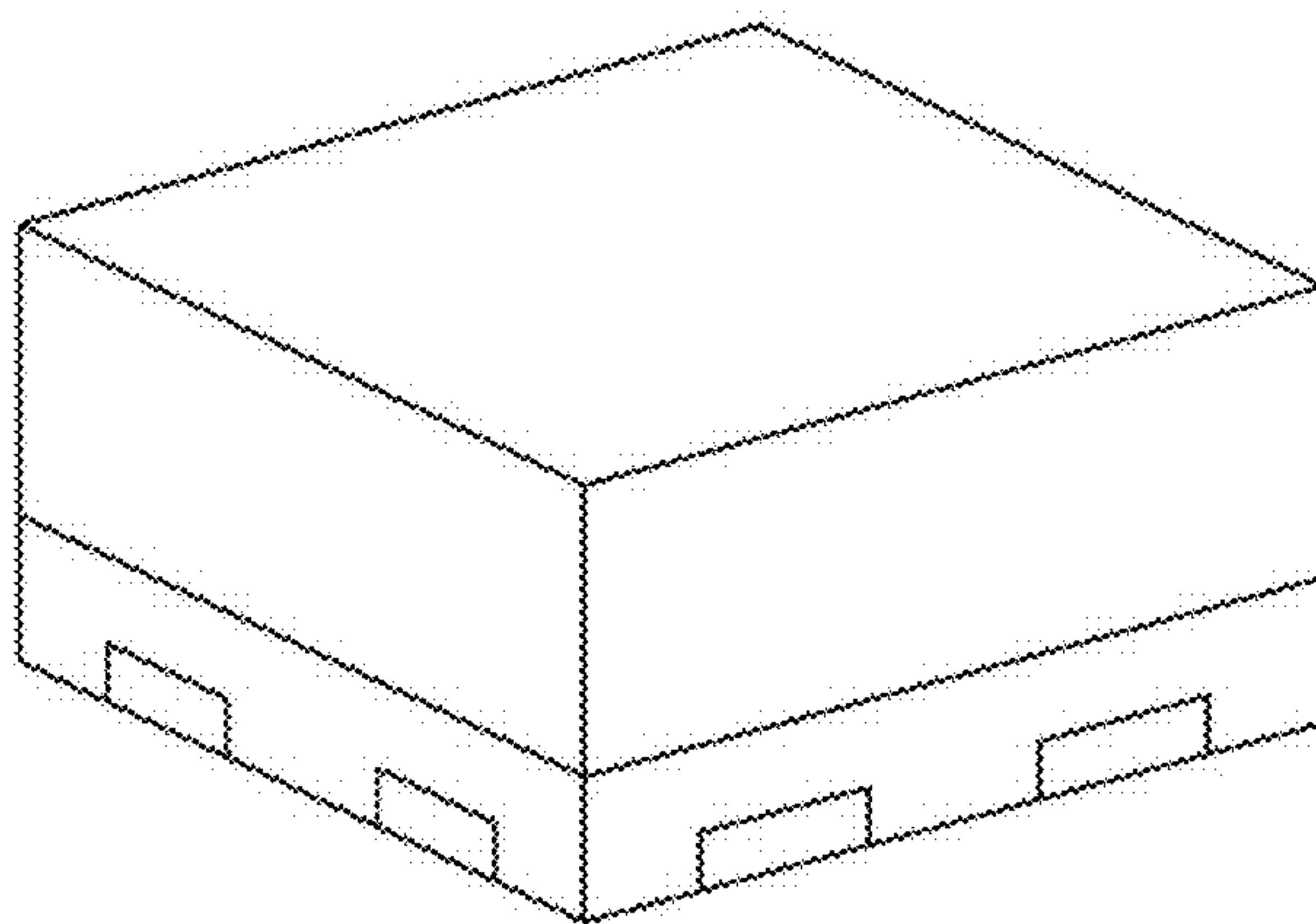


FIG. 7

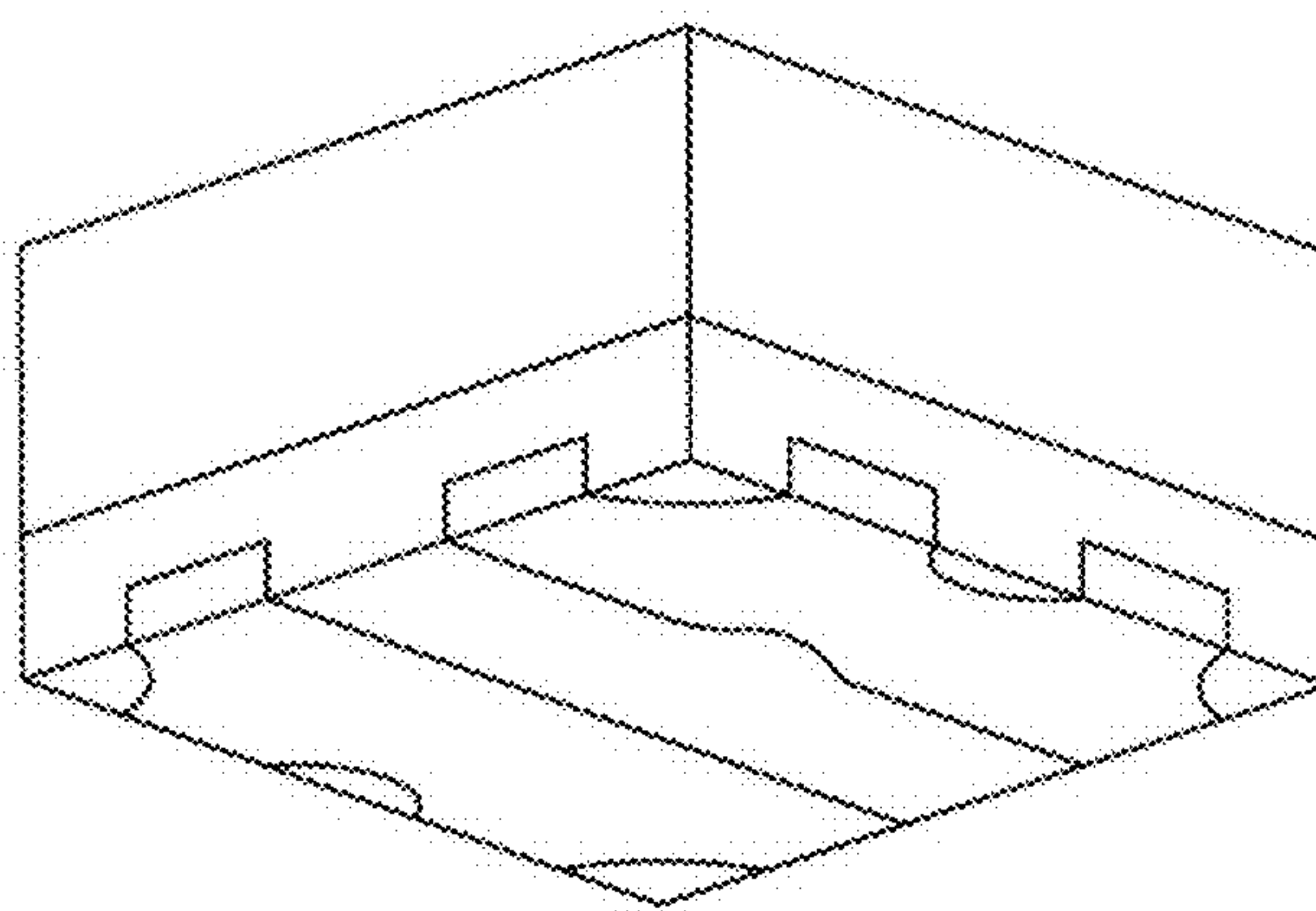


FIG. 8

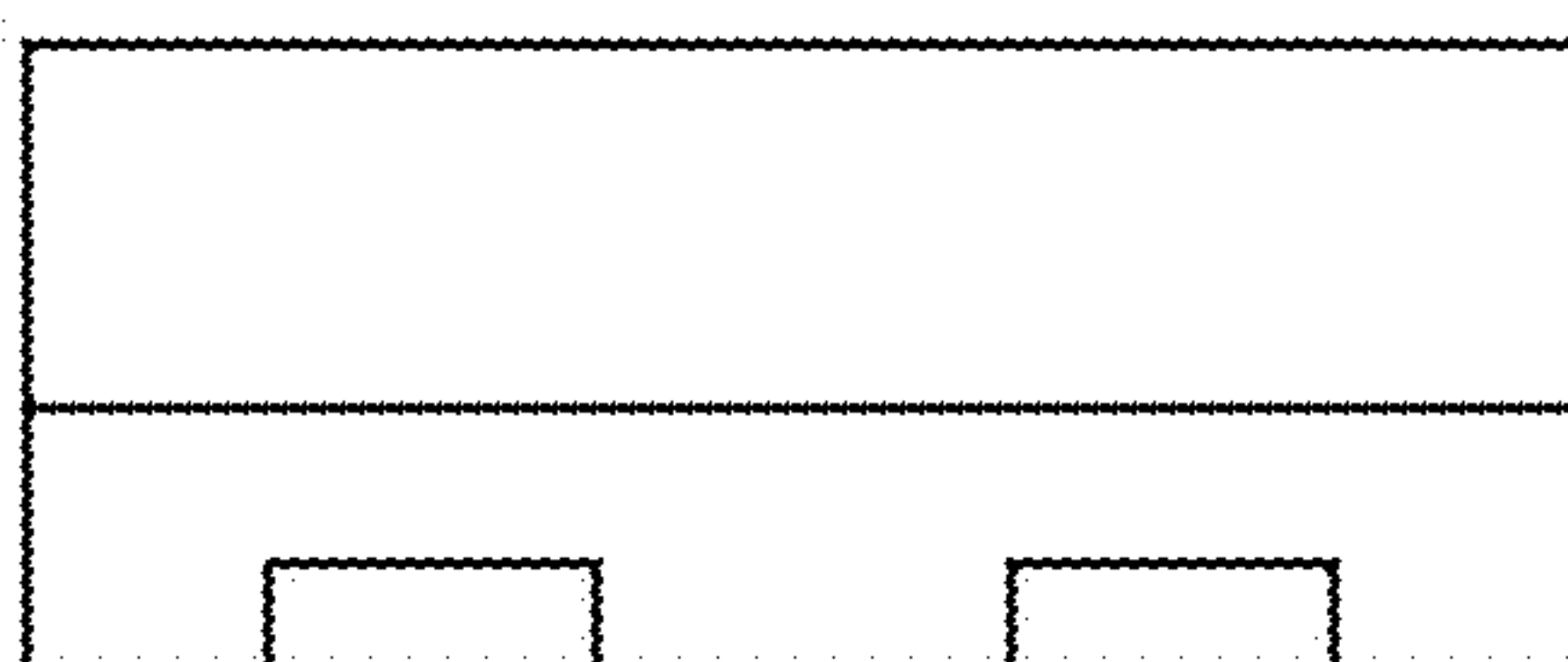


FIG. 9

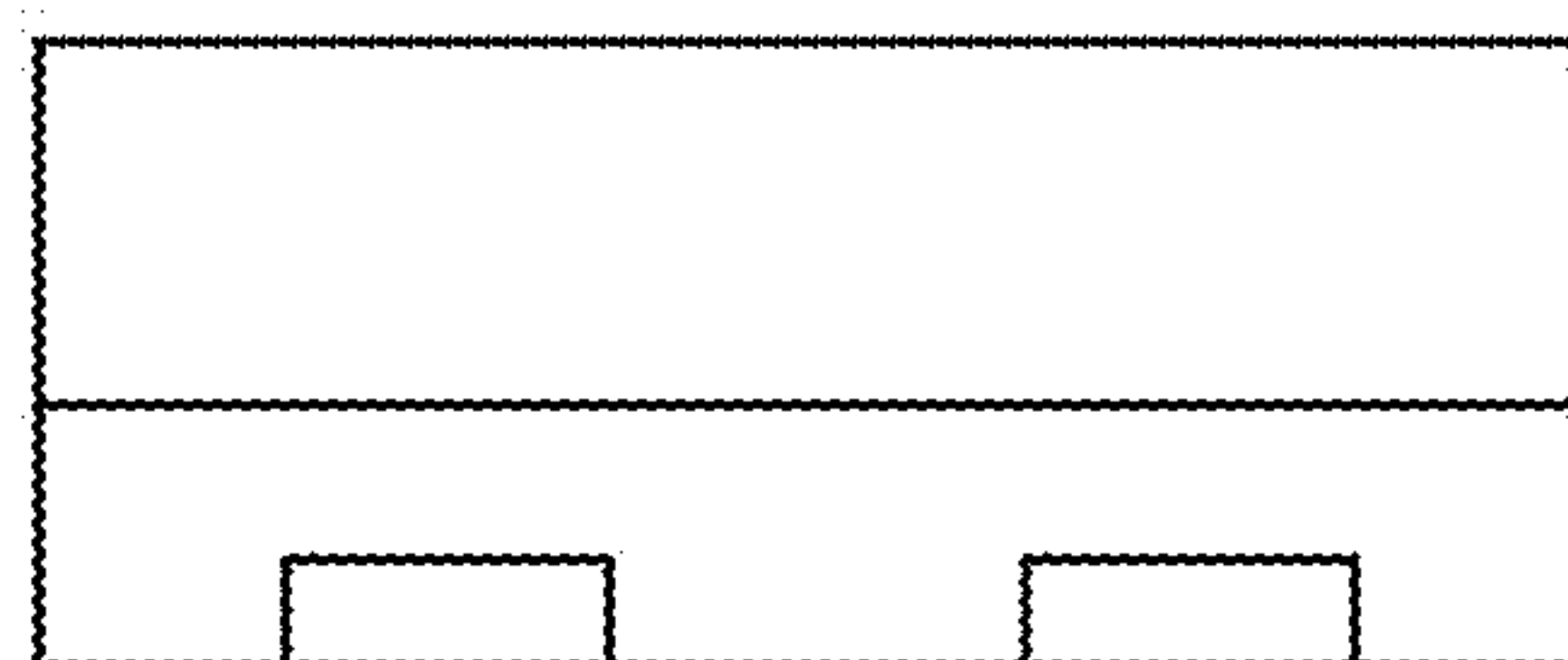


FIG. 10

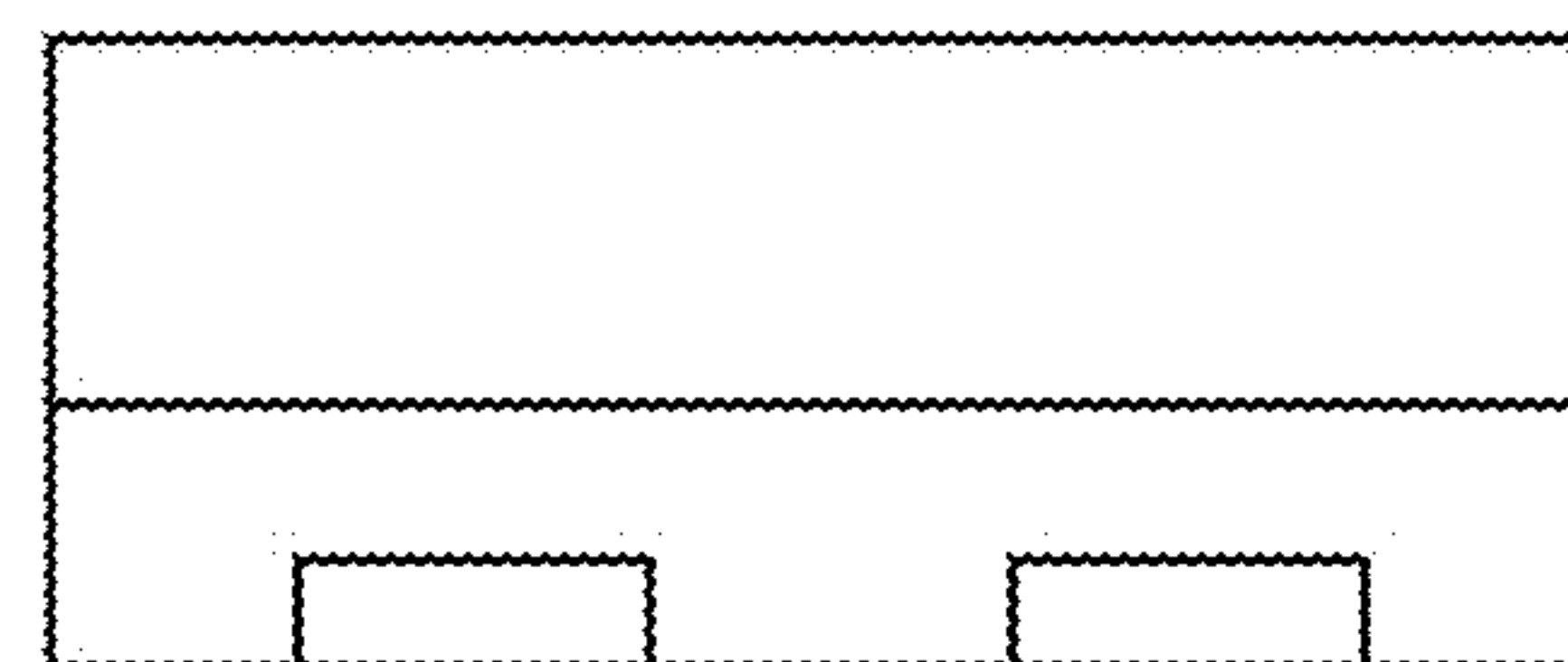


FIG. 11

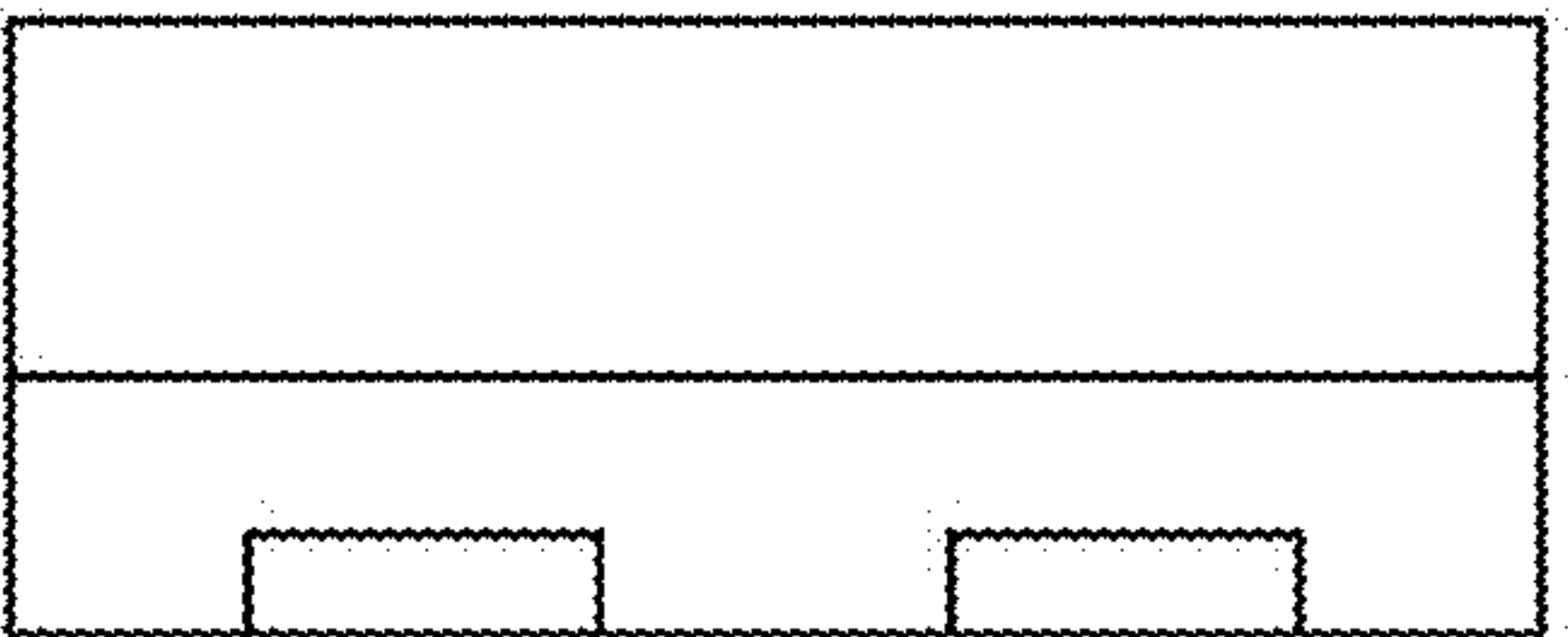


FIG. 12

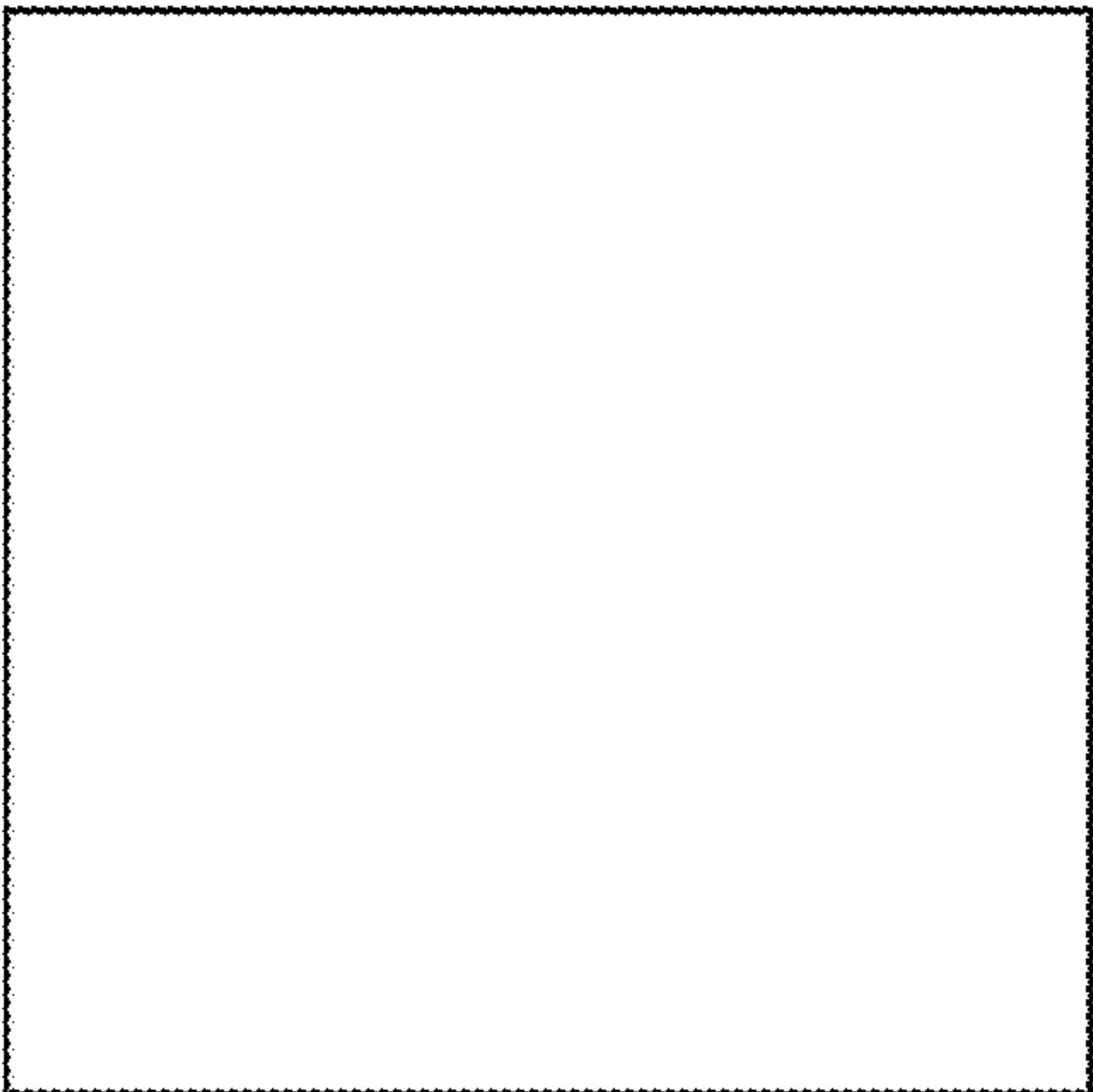


FIG. 13

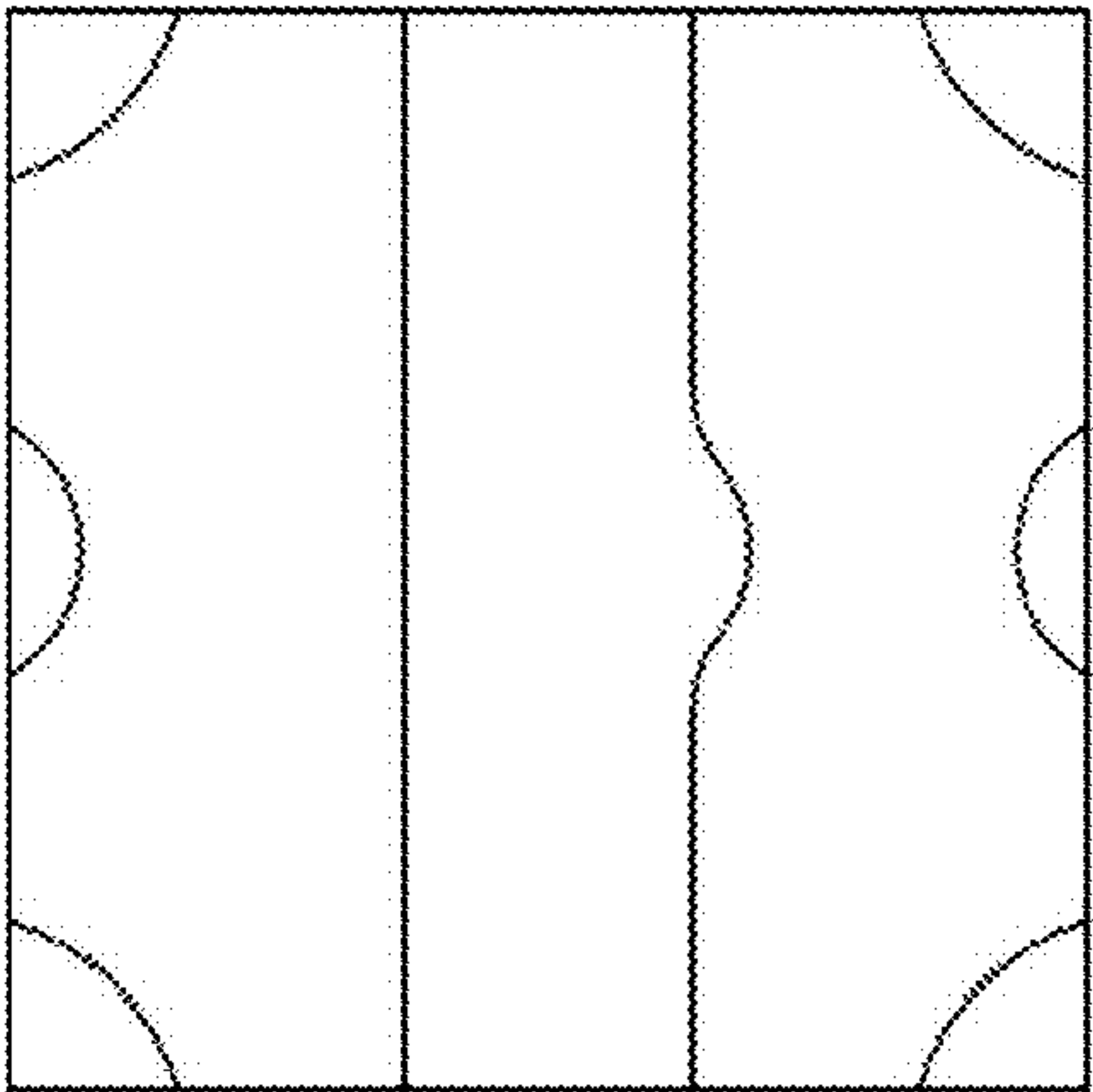


FIG. 14

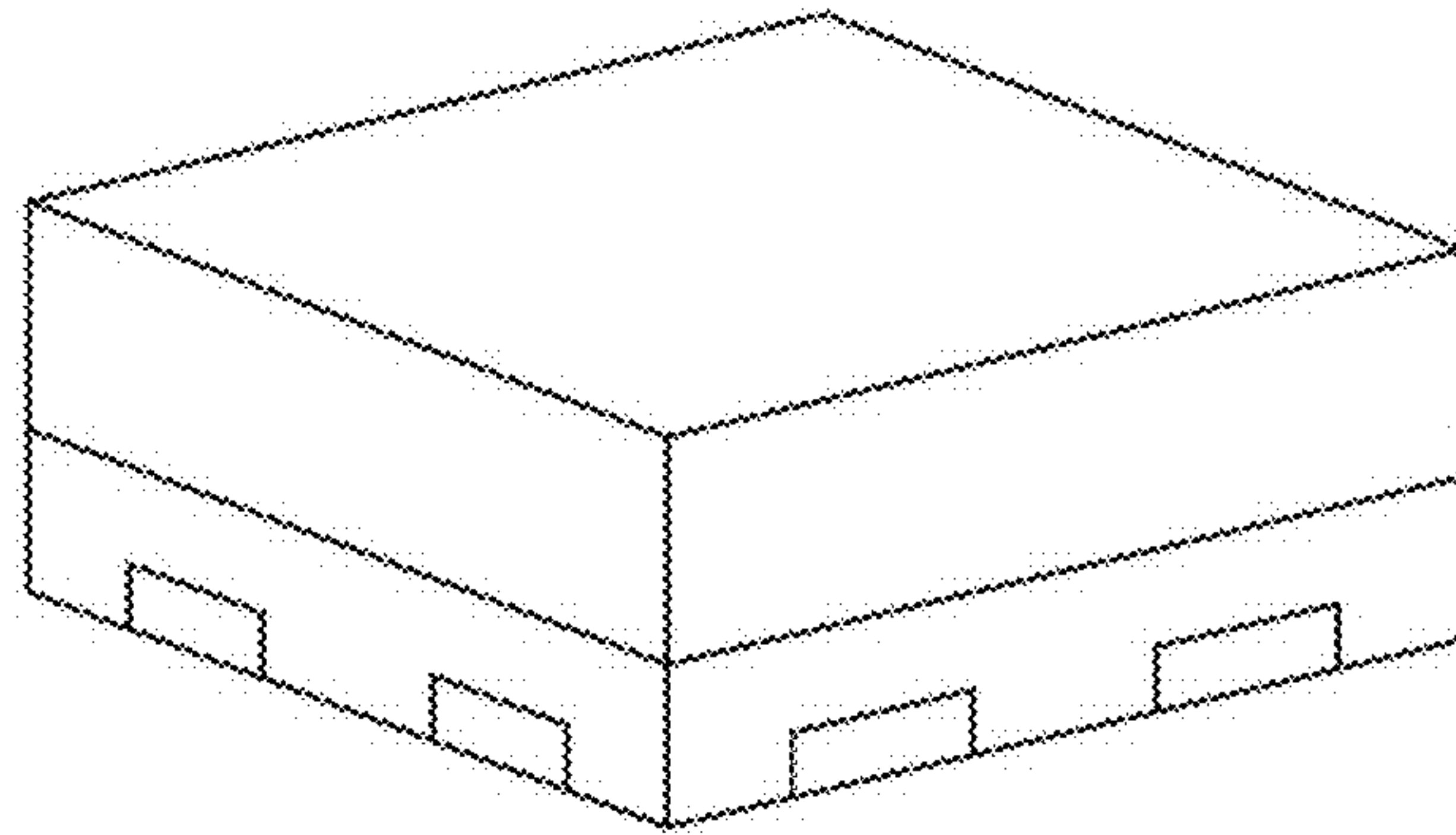


FIG. 15

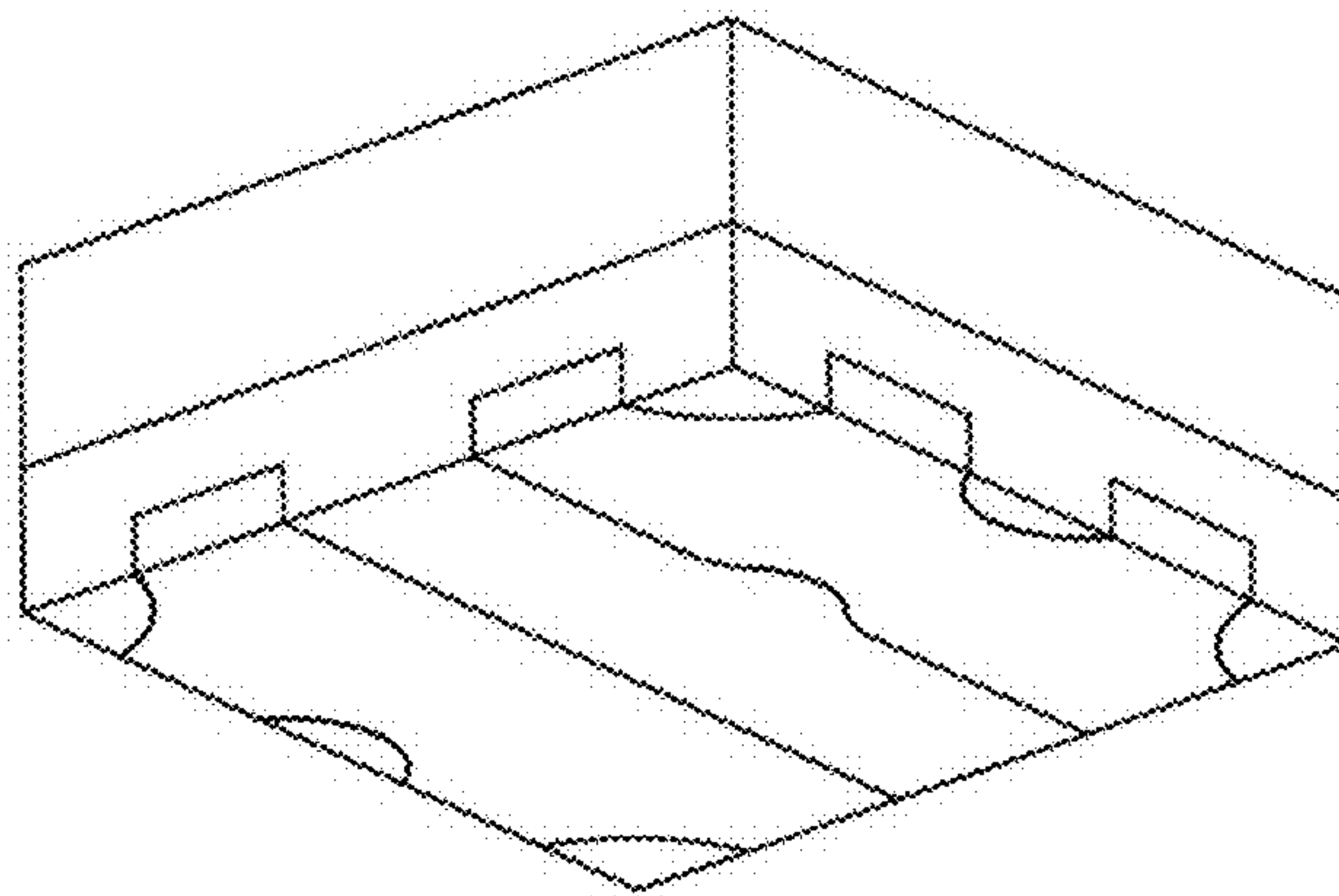


FIG. 16

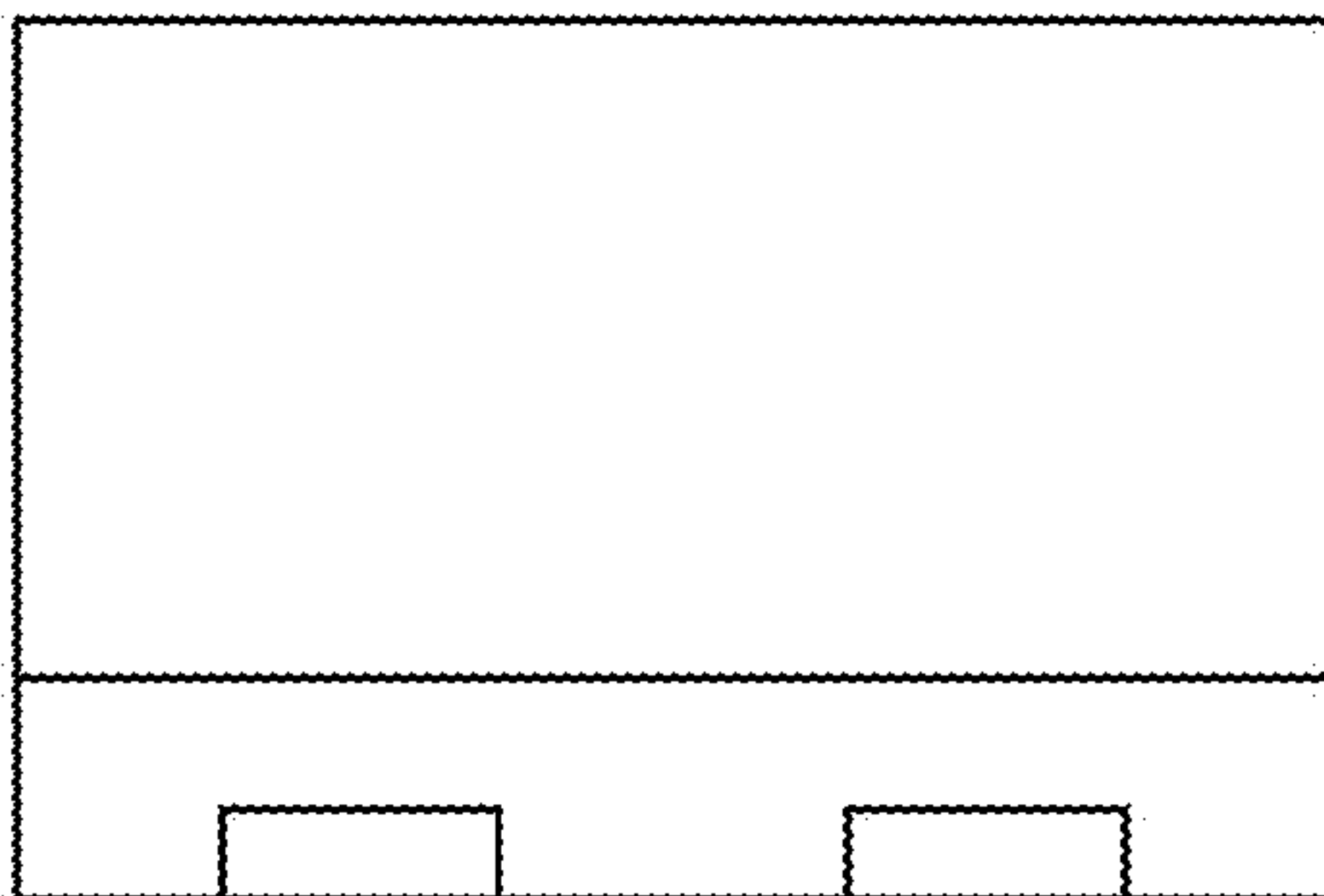


FIG. 17

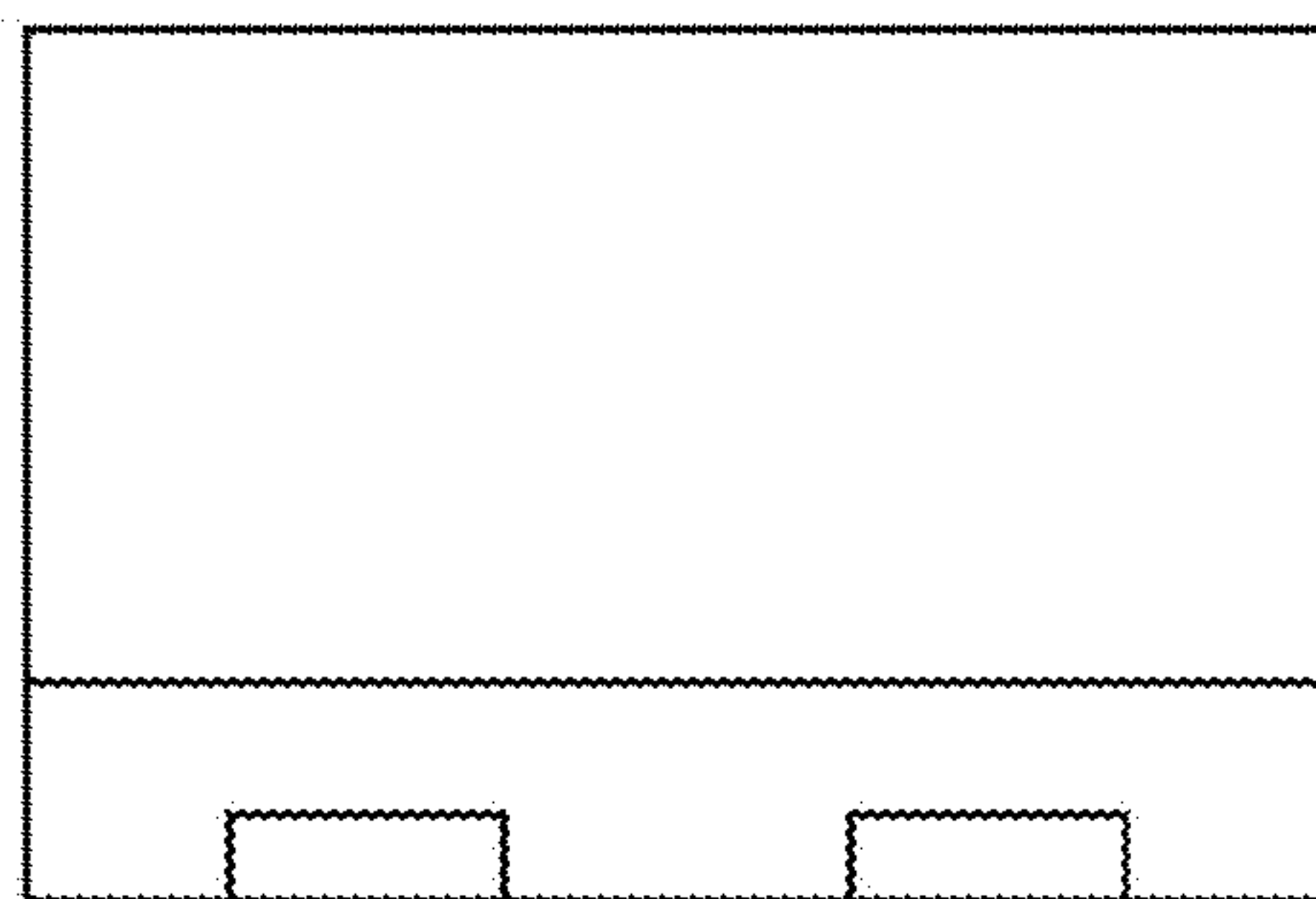


FIG. 18

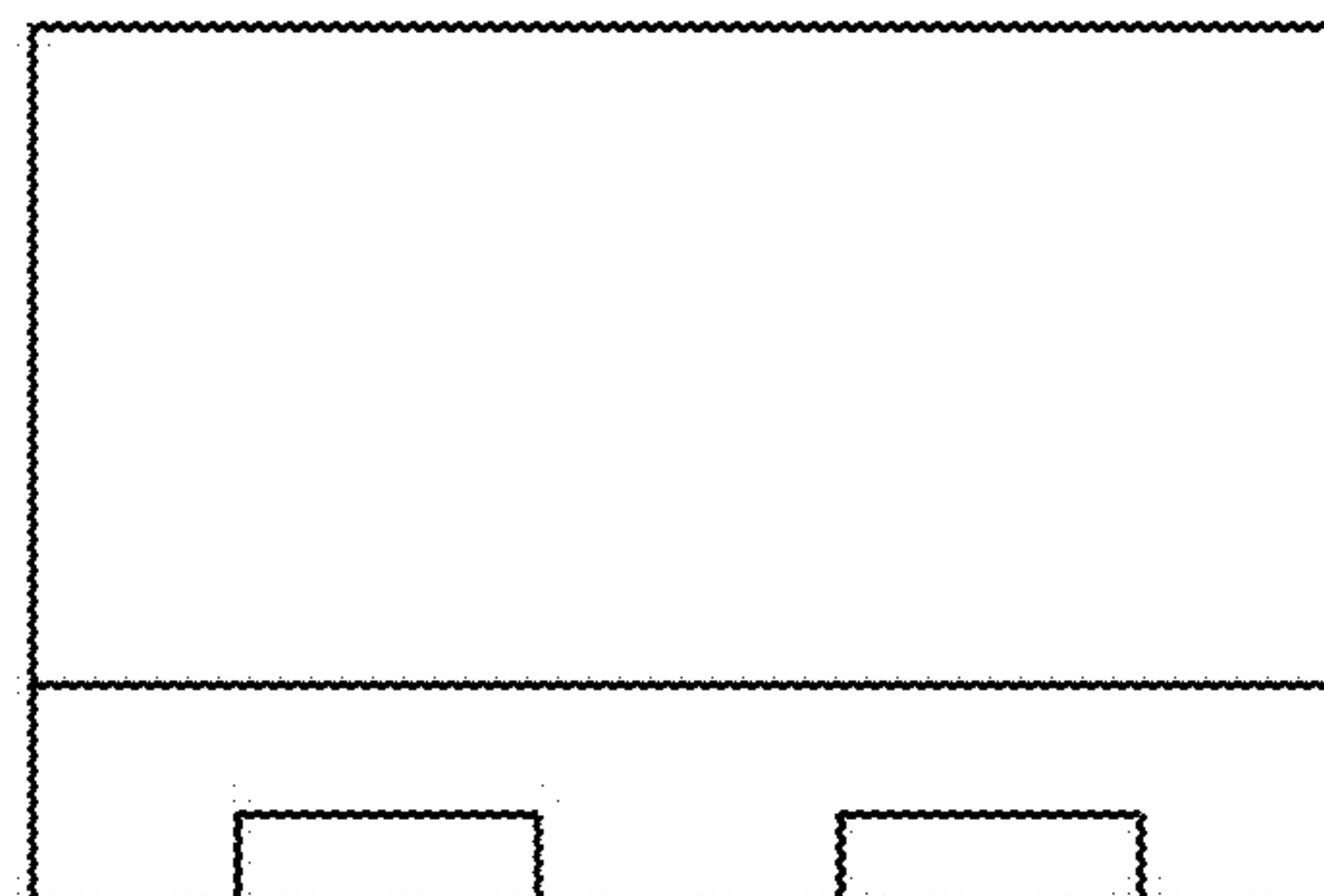


FIG. 19

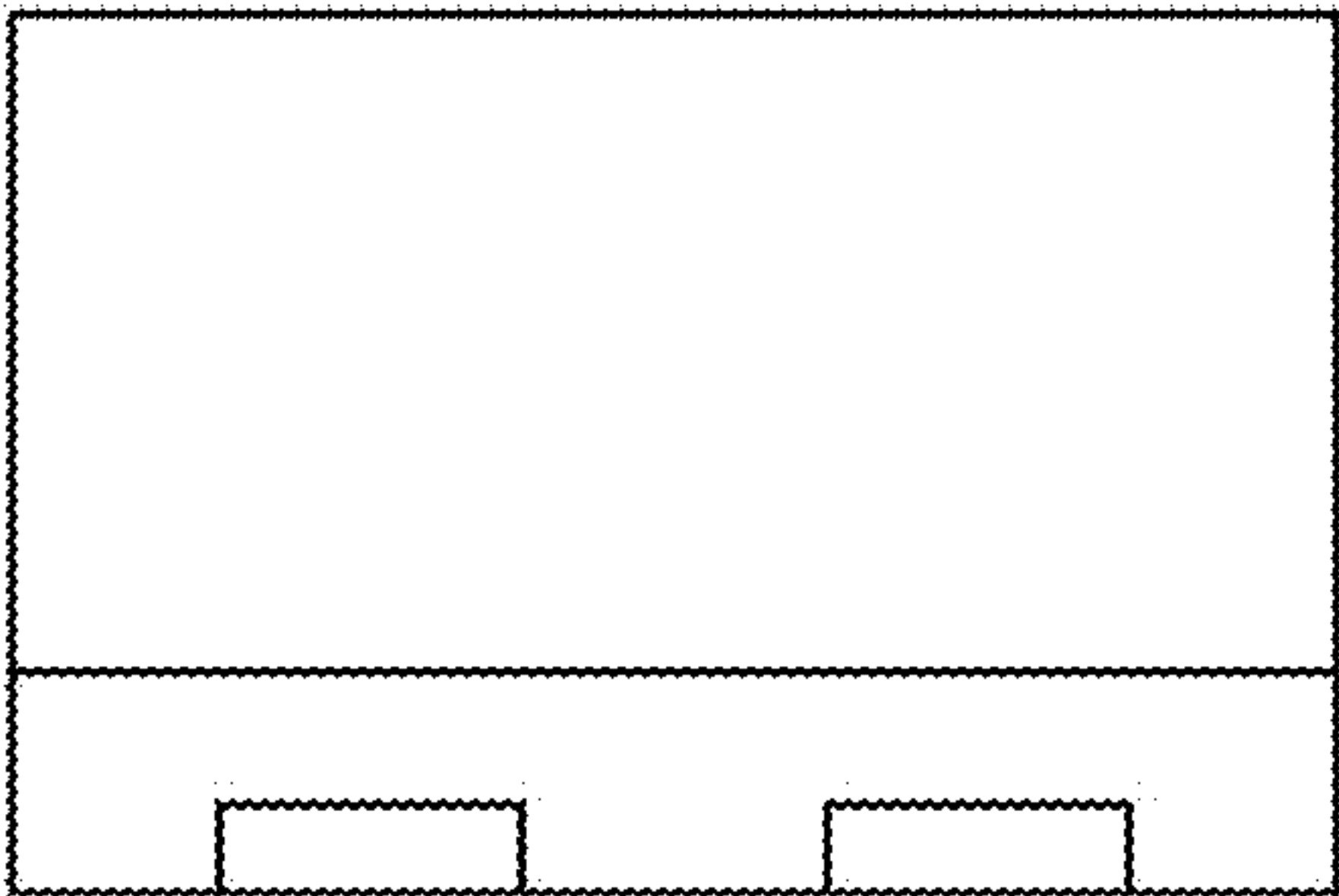


FIG. 20

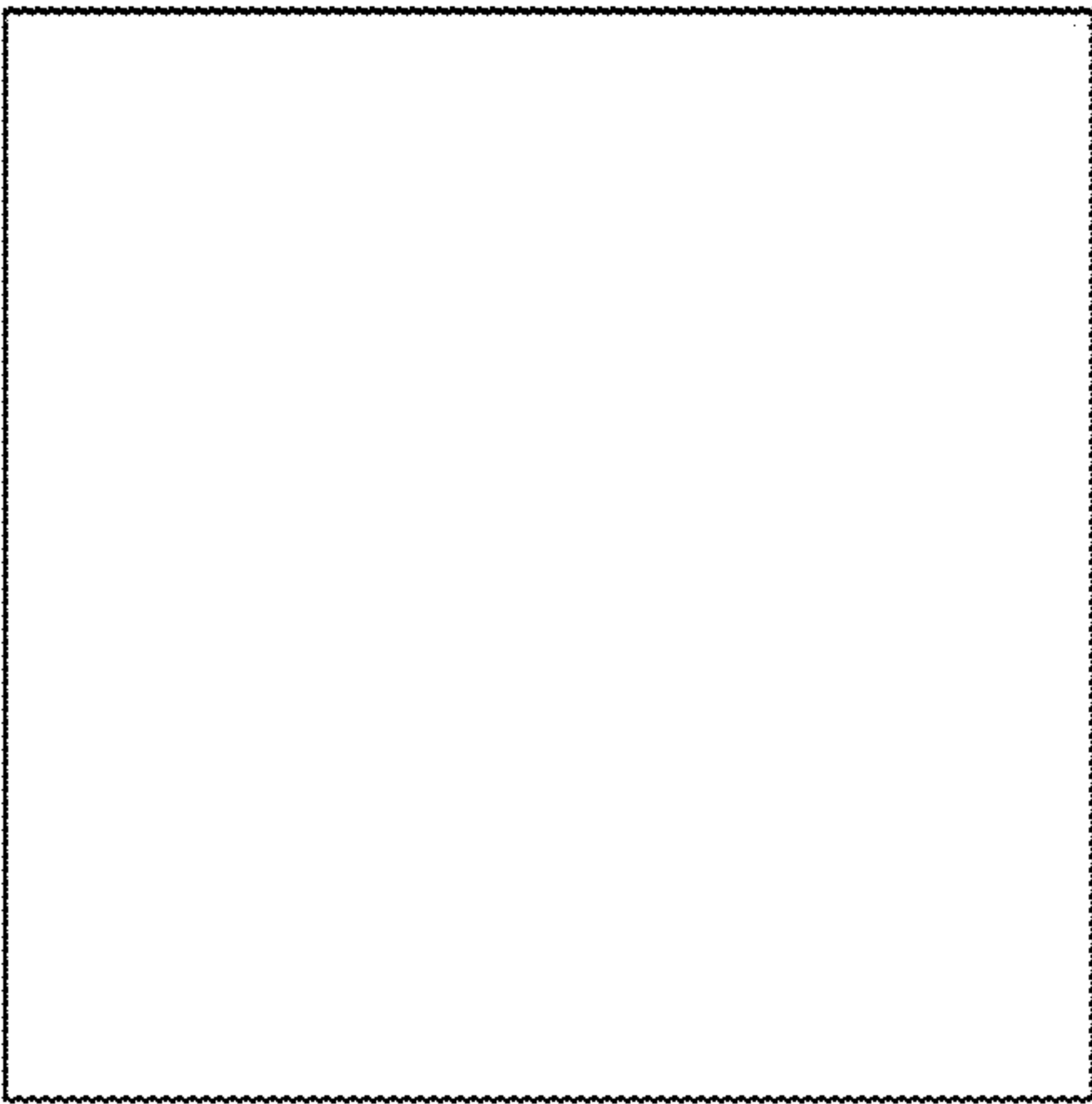


FIG. 21

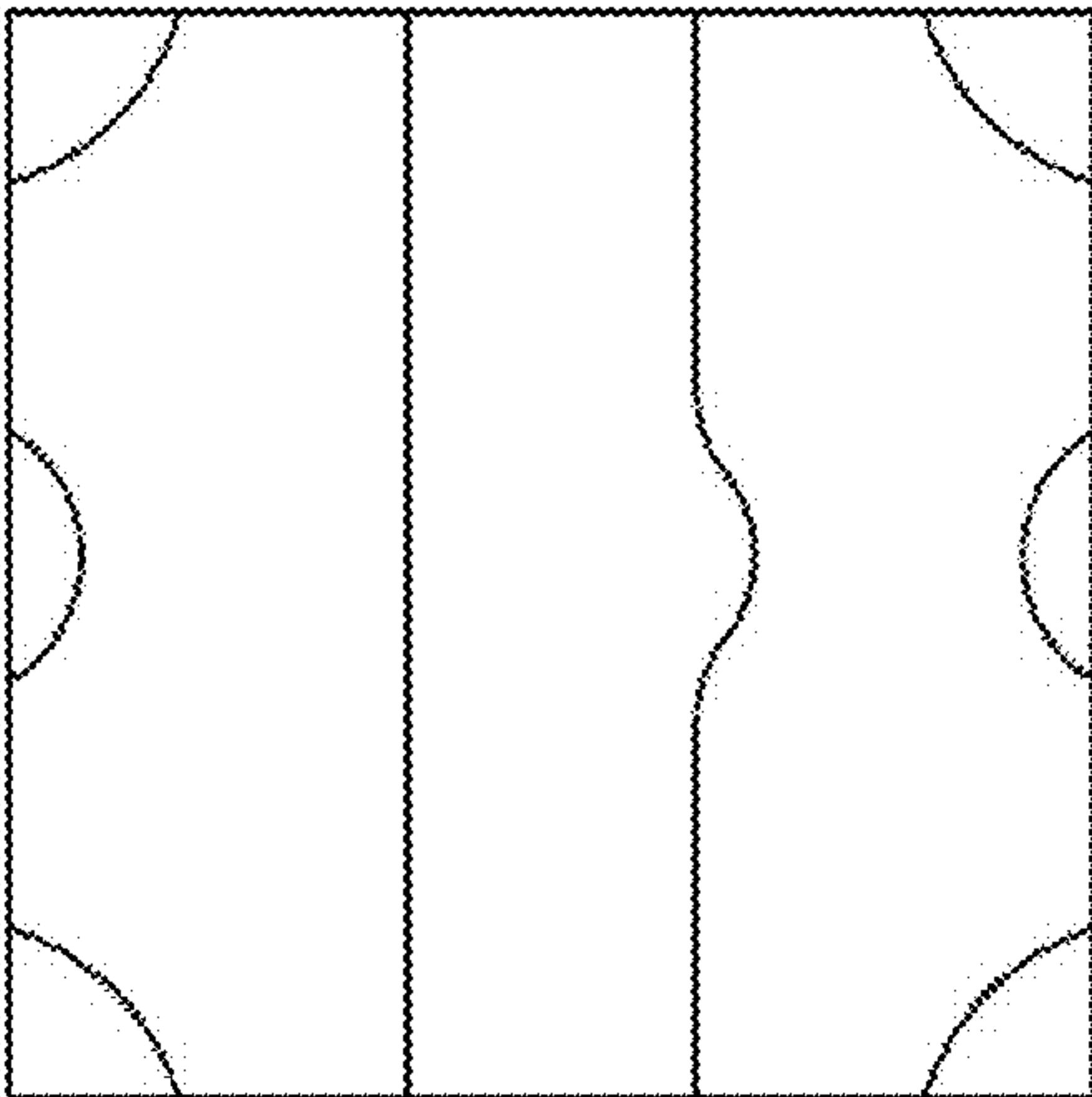


FIG. 22

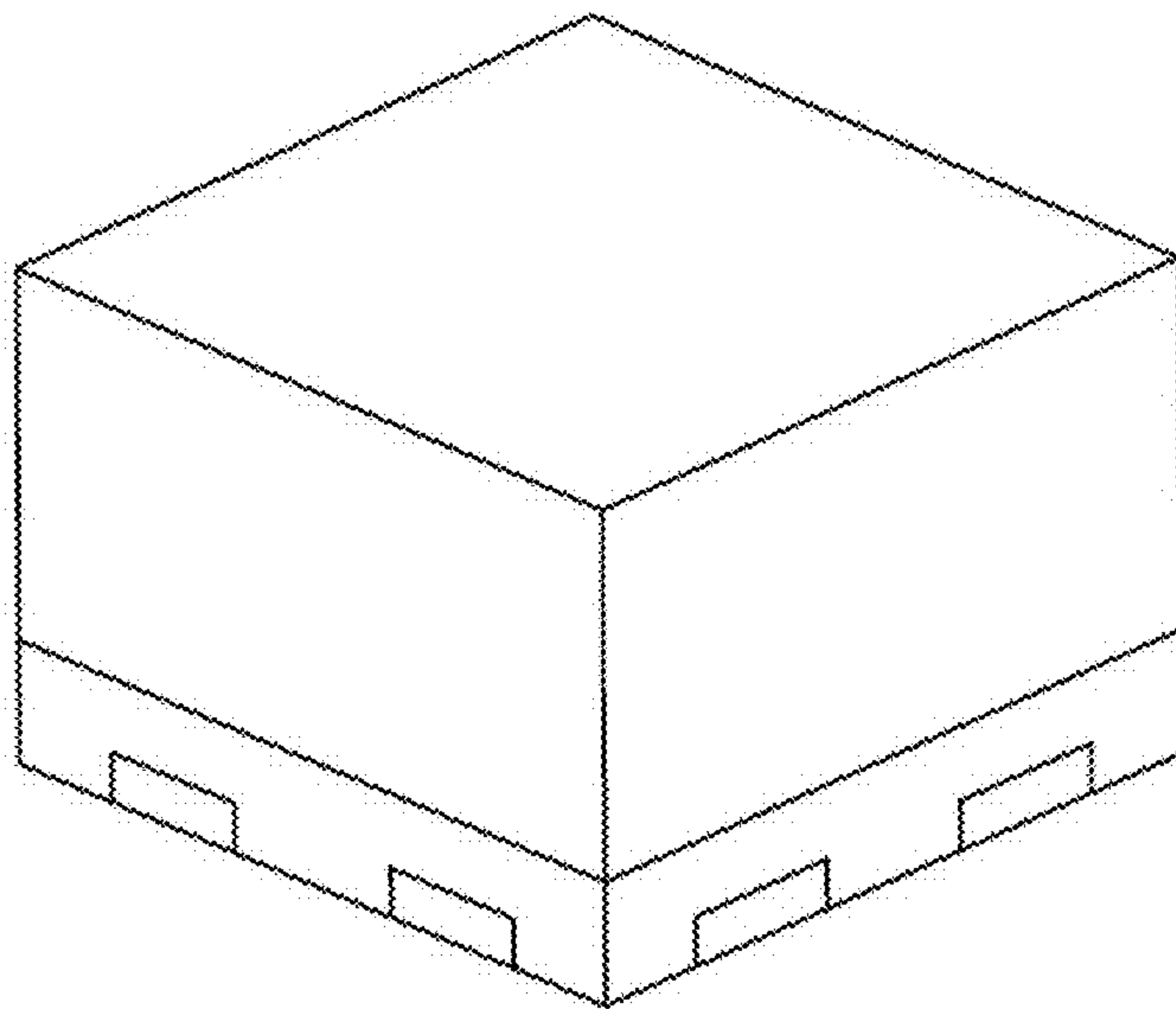


FIG. 23

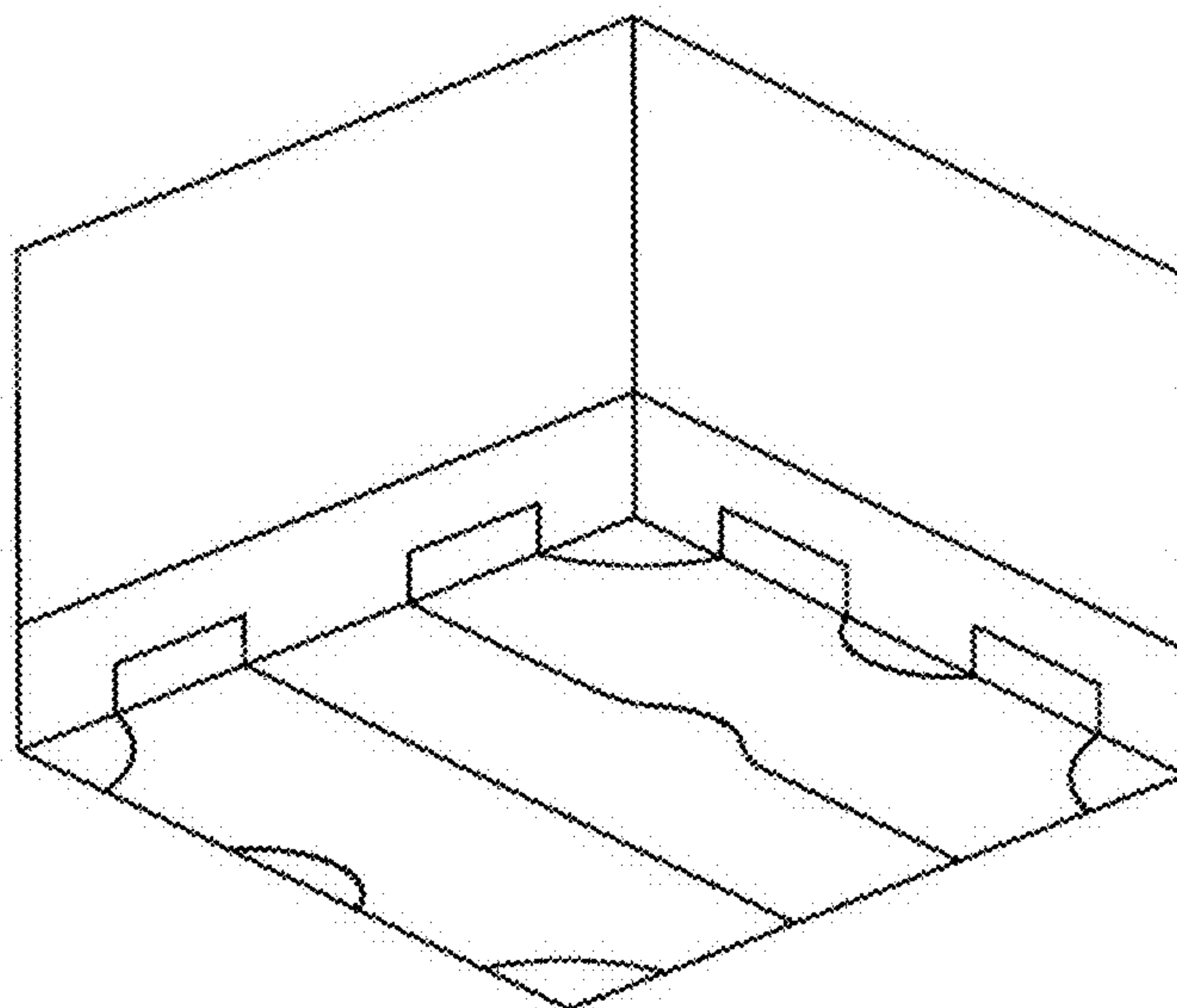


FIG. 24